



DETAIL-A

NOTES:

1. PLATING:
Ni : 50~300 MICRO INCHES
Au : 75 MICRO INCHES MIN.
2. SEAL AREA TO BE METALLIZED.
3. DIE ATTACH AREA TO BE METALLIZED.
4. SEAL RING AND DIE ATTACH PAD TO BE FLOATING FROM ANY PINS.
5. LEAD RESISTANCE : 0.20 OHM MAX.
6. WIRE BOND PAD CONNECTED TO CORRESPONDED OUTER PAD.

MODIFICATION						NAME 16 LEAD SIDE BRAZED PACKAGE	TOLERANCE UNLESS OTHERWISE SPECIFIED $\pm .005$ THIRD ANGLE PROJECTION	DRAWN	CHECKED	APPROVED	DATE
								S.A	TD/H/SN	H.SA	NG/2/76
	CHANGED		DATE	DRAWN	CHECKED	APPROVED		DRAWING NO.			SHEET 1/5